



Final Product Change Notification **Withdrawal**

201903005F01W : Withdrawal: ASEK Grinding/Sawing Transferring to ATKH - NX20P5090UK

Note: This notice is NXP Company Proprietary.

Issue Date: May 13, 2022 **Effective date:** Aug 11, 2022

Management summary

BE2 (back half of the Assembly process) transferring from ASEK to ATKH (grinding/sawing/marketing and packing). BE2 will be enabled in ATKH.

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input checked="" type="checkbox"/> Other: BE2 process transferring (Grinding/Sawing/Marking/Packing) | | | |

PCN Overview

Description

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2 (back half of the Assembly process).

The flow allows for manufacturing flexibility and helps ensure customer supply.

BE2(back half of the Assembly process) (grinding/sawing/marketing and Packing) will be enabled in ATKH.

There's no change in Form, Fit or Function.

Reason

Expanding the current flow which is currently limited to an ASE Assembly to allow for ATKH BE2.

The flow allows for manufacturing flexibility and helps ensure customer supply.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not Applicable

Production

Planned first shipment

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jun 12, 2022.

Remarks

Withdraw the FPCN 201903005F01, the BE2 tranfer of NX20P5090 was cancelled.

Withdrawal Information

NXP decided to stop the NX20P5090 BE2 expansion because the current ASEK has enough capacity to support customer demands.

Contact and Support

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.
For specific questions on this notice or the products affected please contact our specialist directly:

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